(19) 日本国特許庁 (JP)

(12) 公開実用新案公報 (U)

(11)实用新案山砌公開番号

実開平4-105590

(43)公開日 平成4年(1992)9月10日

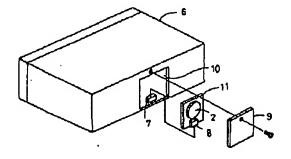
(51) Int.Cl. ⁵		識別配号	庁內發理番号	FΙ				技術是	示简所
H05K	7/12	w	8823-4E						
G06F	1/26								
H01M	2/10	В	7356-4K						
			7832-5B	G 0 6 F	1/00		331 A		
			·	:	密查請求	未醋求	簡求項の	数1(全	2 頁)
(21) 出期番号		実願平3-15821	(71)出阐人	000001487 クラリオン株式会社					
(00) IIII85 F7		平成3年(1991) 2月					ມ 5 丁目35∜	母2号	
(22) 出額日		平成3年(1931) 23	120	(72)考案者	原和目		_ 0 ,00.		
				(10)-738-8		のな区台に	11.6 丁目35 4	路2号	クラリ
					> 113	400, 1001 4			

(54) 【考案の名称】 電子機器のメモリーバツクアツブ用電池取付構造

(57)【要約】

[目的] 電子機器のメモリーパックアップ用電池の交換を容易にし、且つ無駄な電池消耗を避ける。

【構成】 コネクターを介して電子機器本体のメイン基 板へ電池基板を溶脱白在に接続可能とした。





Partial English-language translations of the references 1, 4 and 7

JP Hei.4-105590 U (from paragraphs 0007 to 0009)

[0007]

[Embodiment]

Hereinafter, an embodiment of the present invention will be explained with reference to the accompanying drawings. Figs. 1 and 2 show the embodiment of the invention.

[8000]

Fig. 1 is a schematic diagram showing the attachment state of the invention, in which an opening portion 10 is defined in the rear surface side of an electronic device 6, and a substrate 11 having a battery 2 for backing-up a memory is coupled through a connector 8 of this substrate to a connector 7 provided on a main substrate.

The opening portion 10 is closed by a lid portion 9 by means of screws after the completion of the connection.

[0009]

Fig. 2 is a schematic diagram showing the attachment relation between the memory back-up battery 2 and the substrate 11 and the attachment relation between the substrate 11 and the main substrate 3.

Electrodes 2a, 2b of the memory back-up battery 2 are soldered on a pattern surface 12, thereby to fix the memory back-up battery to the substrate 11. The connector 8 is electrically fixed to the pattern

surface of the substrate 11 by means of the soldering. The connector 7 is electrically fixed to the main substrate 3 by means of the soldering. Thus, the substrate 11 is coupled to the connector 7 through the connector 8 and so coupled to the main substrate 3.